



### Absolute Maximum Ratings\*

Voltage on any pin relative to VSS ..... -0.5V to 7.0V  
 Operating Temperature TA (Ambient)  
     Commercial ..... 0°C to +70°C  
     Industrial ..... -40°C to +85°C  
     Military ..... -55°C to +125°C  
 Storage Temperature  
     Plastic ..... -55°C to +125°C  
     Ceramic ..... -65°C to +150°C  
 Power Dissipation ..... 1 Watt  
 Output Current ..... 20 mA  
 Junction Temperature, TJ ..... 175°C

\*Stress greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions greater than those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

### Recommended DC Operating Conditions

Parameter	Sym	Min	Typ	Max	Units
Supply Voltage	VCC	4.5	5.0	5.5	V
Supply Voltage	VSS	0	0	0	V
Input High Voltage	VIH	2.2	--	6.0	V
Input Low Voltage	VIL	-0.3	--	0.8	V

### AC Test Conditions

Input Pulse Levels ..... VSS to 3.0V  
 Input Rise and Fall Times ..... 5ns  
 Input and Output Timing Levels ..... 1.5V  
 Output Load ..... 1TTL, CL = 30pF  
 (note: For TEHQZ, TGHQZ and TWLQZ, CL = 5pF)

### DC Electrical Characteristics

Parameter	Sym	Conditions	Min	Typ*	Max	Units	
Operating Power Supply Current	ICC1	$\bar{W}, \bar{E} = VIL, I/O = 0mA, \text{Min Cycle}$ $S = VIH, \text{Min Cycle}$	--	80	150	mA	
Standby (TTL) Power Supply Current	ICC2	$\bar{E} \geq VIH, VIN \leq VIL, VIN \geq VIH$	--		30	mA	
Full Standby Power Supply Current	ICC3	$\bar{E} \geq VCC-0.2V$	CS	--	1	10	mA
		$VIN \geq VCC-0.2V \text{ or } VIN \leq 0.2V$	LPS/PS		--	5	mA
Input Leakage Current	ILI	$VIN = 0V \text{ to } VCC$	--	--	±5	µA	
Output Leakage Current	ILO	$V I/O = 0V \text{ to } VCC, \bar{E} \geq VIH$	--	--	±10	µA	
Output High Voltage	VOH	$IOH = -4.0mA$	2.4	--	--	V	
Output Low Voltage	VOL	$IOL = 8.0mA$	--	--	0.4	V	

\*Typical = TA = 25°C, VCC = 5.0V

### Truth Table

$\bar{G}$	$\bar{E}$	S	$\bar{W}$	Mode	Output	Power
X	H	X	X	Standby	High Z	ICC2, ICC3
X	X	L	X	Output Deselect	High Z	ICC1
H	L	H	H	Output Deselect	High Z	ICC1
L	L	H	H	Read	DOUT	ICC1
X	L	H	L	Write	DIN	ICC1

### Capacitance

(f=1.0MHz, VIN=VCC or VSS)

Parameter	Sym	Max		Unit
		LCC Plastic DIP, SOJ	Ceramic DIP, FP CSOJ	
Input (Except DQ Pins)	CI	6	12	pF
Control (DQ Pins)	CD/Q	8	14	pF

These parameters are sampled, not 100% tested.

## AC Characteristics

### Read Cycle

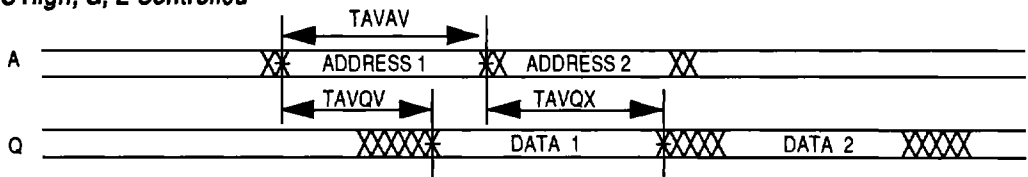
Parameter	Symbol	20ns		25ns		35ns		45ns		55ns		Units
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Read Cycle Time	TAVAV	20		25		35		45		55		ns
Address Access Time	TAVQV		20		25		35		45		55	ns
Chip Enable Access Time	TELQV $\bar{E}$		20		25		35		45		55	ns
	TSHQV $S^*$		20		25		35		45		55	ns
Chip Enable to Output in Low Z (1)	TELQX $\bar{E}$	3		3		3		3		3		ns
	TSHQX $S^*$	3		3		3		3		3		ns
Chip Disable to Output in High Z (1)	TEHQZ $\bar{E}$		10		12		20		25		25	ns
	TSLQZ $S^*$		10		12		20		25		25	ns
Output Hold from Address Change	TAVQX	3		3		3		3		3		ns
Output Enable to Output Valid	TGLOV		8		10		20		25		25	ns
Output Enable to Output in Low Z (1)	TGLOX	0		0		0		0		0		ns
Output Disable to Output in High Z (1)	TGHQZ		8		10		20		25		25	ns

Note 1: Parameter guaranteed, but not tested.

\*ED188130 Only

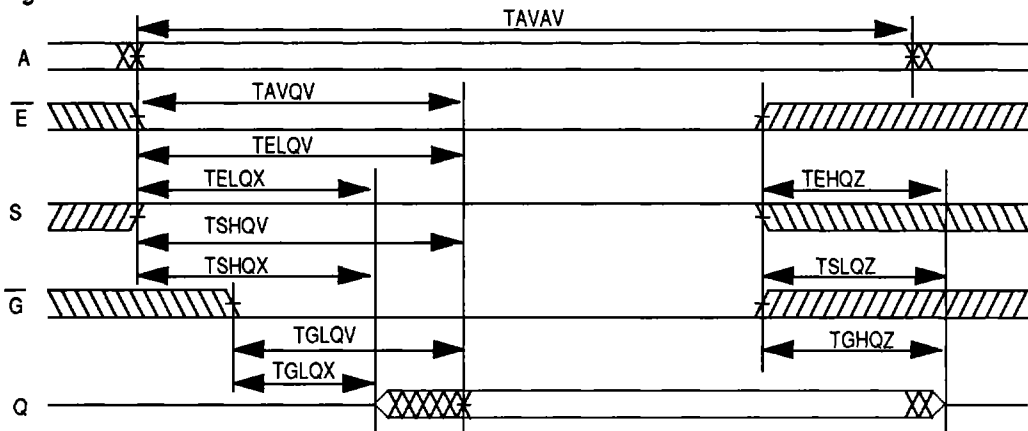
### Read Cycle 1

*W, S High; G, E Controlled*



### Read Cycle 2

*W High*



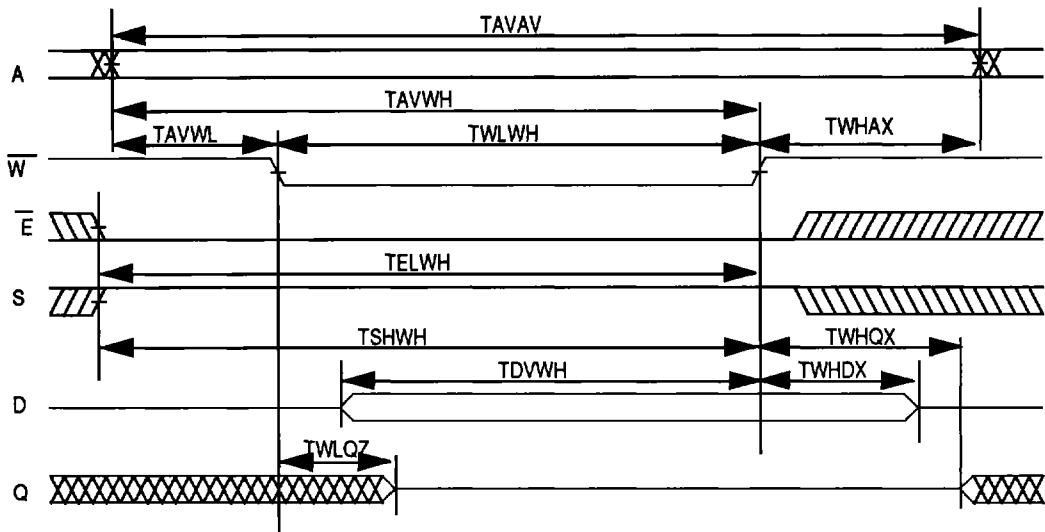
**AC Characteristics**  
**Write Cycle**

Parameter	Symbol		20ns		25ns		35ns		45ns		55ns		Units
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Write Cycle Time	TAVAV		20		25		35		45		55		ns
Chip Enable to End of Write	TELWH	$\overline{E}$	15		20		30		35		40		ns
	TELEH	$\overline{E}$	15		20		30		35		40		ns
	TSHWH	S*	15		20		30		35		40		ns
	TSHSL	S*	15		20		30		35		40		ns
Address Setup Time	TAVWL	$\overline{W}$	0		0		0		0		0		ns
	TAVEL	$\overline{E}$	0		0		0		0		0		ns
	TAVSH	S*	0		0		0		0		0		ns
Address Valid to End of Write	TAVWH		15		20		30		35		40		ns
Write Pulse Width	TWLWH	$\overline{W}$	15		20		30		35		40		ns
	TWLEH	$\overline{E}$	15		20		30		35		40		ns
	TWLSL	S*	15		20		30		35		40		ns
Write Recovery Time	TWHAX	$\overline{W}$	0		0		0		0		0		ns
	TEHAX	$\overline{E}$	0		0		0		0		0		ns
	TSLAX	S*	0		0		0		0		0		ns
Data Hold Time	TWHDX	$\overline{W}$	0		0		0		0		0		ns
	TEHDX	$\overline{E}$	0		0		0		0		0		ns
	TSLDX	S*	0		0		0		0		0		ns
Write to Output in High Z (1)	TWLQZ		0	8	0	10	0	15	0	20	0	20	ns
Data to Write Time	TDVWH	$\overline{W}$	12		15		20		25		25		ns
	TDVEH	$\overline{E}$	12		15		20		25		25		ns
	TDVSL	S*	12		15		20		25		25		ns
Output Active from End of Write (1)	TWHQX		3		3		3		3		3		ns

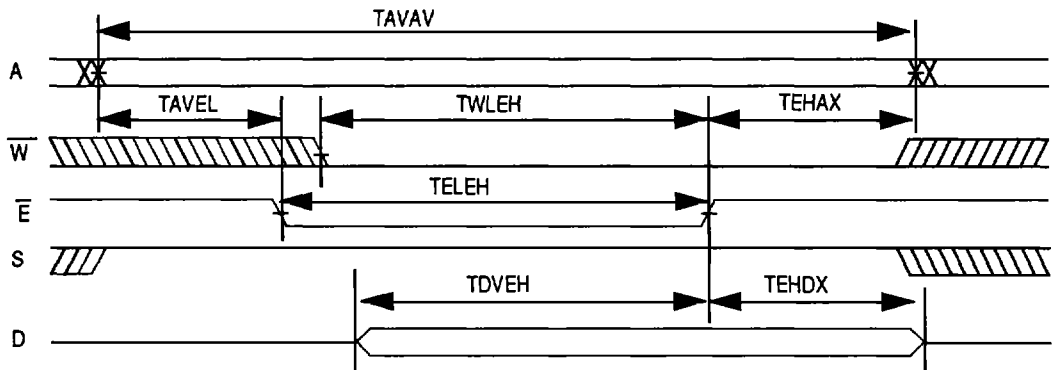
Note 1: Parameter guaranteed, but not tested.

\*ED188130 Only.

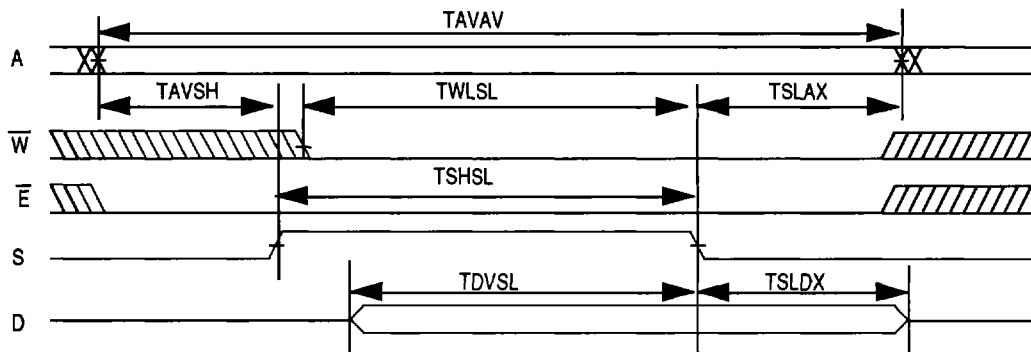
**Write Cycle 1**  
**Late Write,  $\bar{W}$  Controlled**



**Write Cycle 2**  
**Early Write, E Controlled**



**Write Cycle 3**  
**Early Write, S Controlled**



### Data Retention Characteristics

(TA = -55°C to +125°C)

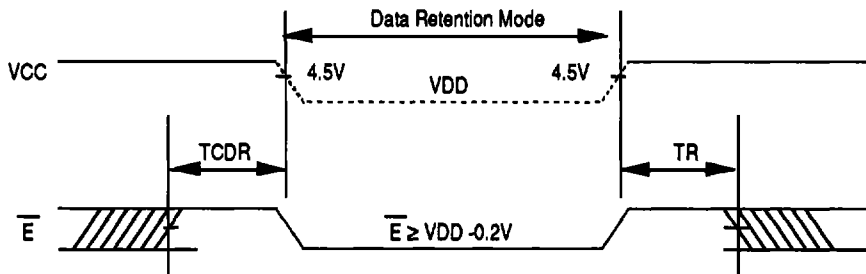
**LPS Versions Only**

(ED188128LPS & ED188130LPS)

Characteristic	Sym	Test Conditions	Min	Typ	Max	Unit
Data Retention Voltage	VDD	VDD = 2.0V	2	--	--	V
Data Retention Quiescent Current	ICCDR	$\bar{E} \geq VDD - 0.2V$	--	0.750	2	mA
Chip Disable to Data Retention Time	TCDR	VIN $\geq$ VDD - 0.2V	0	--	--	ns
Operation Recovery Time	TR	or VIN $\leq$ 0.2V	TAVAV*	--	--	ns

\*Read Cycle Time

### Data Retention $\bar{E}$ Controlled



### Data Retention S Controlled

